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ABSTRACT OF THE DISCLOSURE

A method of manufacturing an integrated circuit (IC) device is discussed. A wafer including multiple dies is processed to form high aspect ratio microstructures along scribe lines that separate the dies. Each microstructure correspond to connection pads of the die. Routers are formed to electrically route a connection pad to the corresponding microstructure. Wafer material is then removed from a second side of the wafer, opposite the first side, to expose the routers at the microstructures. Contacts are formed on the second side that electrically connect with the routers at the microstructures to thereby electrically connect with the connection pads on the first side. The dies are separated along the scribe lines, between the microstructures to produce individualized dies. An IC device including a separated die is also disclosed.



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